

L Numb r	Hits	Search Text	DB	Tim stamp
1	1577	438/629,637.ccls.	USPAT	2003/06/05 13:11
2	649	438/639,640.ccls.	USPAT	2003/06/05 13:11
3	275	438/667,668.ccls.	USPAT	2003/06/05 13:12
4	1018	438/672,675.ccls.	USPAT	2003/06/05 13:12
5	1113	257/774.ccls.	USPAT	2003/06/05 13:13
6	206015	(hole contact via open\$6 trench groov\$3 cavit\$4) and (etch\$3 hollow\$3) and (conduct\$6 metl\$6)	USPAT	2003/06/05 13:17
7	84860	(hole contact via open\$6 trench groov\$3 cavit\$4) same (etch\$3 hollow\$3) same (conduct\$6 metal\$6)	USPAT	2003/06/05 13:21
8	20259	((hole contact via open\$6 trench groov\$3 cavit\$4) same (etch\$3 hollow\$3) same (conduct\$6 metal\$6)) and ((hole contact via open\$6 trench groov\$3 cavit\$4) adj2 (etch\$3 hollow\$3))	USPAT	2003/06/05 13:19
9	9297	(((hole contact via open\$6 trench groov\$3 cavit\$4) same (etch\$3 hollow\$3) same (conduct\$6 metal\$6)) and ((hole contact via open\$6 trench groov\$3 cavit\$4) adj2 (etch\$3 hollow\$3))) and ((hole contact via open\$6 trench groov\$3 cavit\$4) adj2 (conduct\$6 metal\$6))	USPAT	2003/06/05 13:19
10	7787	((((hole contact via open\$6 trench groov\$3 cavit\$4) same (etch\$3 hollow\$3) same (conduct\$6 metal\$6)) and ((hole contact via open\$6 trench groov\$3 cavit\$4) adj2 (etch\$3 hollow\$3))) and ((hole contact via open\$6 trench groov\$3 cavit\$4) adj2 (conduct\$6 metal\$6))) and (substrate wafer)	USPAT	2003/06/05 13:19
11	7850	((hole contact via open\$6 trench groov\$3 cavit\$4) same (etch\$3 hollow\$3) same (conduct\$6 metal\$6)) and ((substrate) adj2 (etch\$3 hollow\$3))	USPAT	2003/06/05 13:20
12	4740	(((hole contact via open\$6 trench groov\$3 cavit\$4) same (etch\$3 hollow\$3) same (conduct\$6 metal\$6)) and ((substrate) adj2 (etch\$3 hollow\$3))) and (bottom rear front)	USPAT	2003/06/05 13:20
13	804	((((hole contact via open\$6 trench groov\$3 cavit\$4) same (etch\$3 hollow\$3) same (conduct\$6 metal\$6)) and ((substrate) adj2 (et h\$3 holl w\$3))) and (b ttom r ar front)) and ((substrate) adj2 (b ttom r ar front))	USPAT	2003/06/05 13:22
14	47488	(h le c ntact via open\$6 trench gr ov\$3 cavit\$4) sam (etch\$3 h ll w\$3) same (conduct\$6 metal\$6)	EPO; JPO; DERWENT; IBM_TDB	2003/06/05 13:22

15	164	((h l c ntact via pen\$6 trench gr ov\$3 cavit\$4) same (tch\$3 h ll w\$3) sam (conduct\$6 m tal\$6)) and ((substrate) adj2 (b ttom r ar fr nt))	EPO; JPO; DERWENT; IBM_TDB	2003/06/05 13:22
16	14283	(h l contact via pen\$6 tr nch gro v\$3 cavit\$4) same (tch\$3 hollow\$3) same (conduct\$6 metal\$6)	US-PGPUB	2003/06/05 13:22
17	760	((hole contact via open\$6 trench groov\$3 cavit\$4) same (etch\$3 hollow\$3) same (conduct\$6 metal\$6)) and ((substrate) adj2 (bottom rear front))	US-PGPUB	2003/06/05 13:23
18	0	philippe-robert\$.in.	USPAT	2003/06/05 13:24
19	0	philippe-robert\$.in.	US-PGPUB	2003/06/05 13:24
20	7	philippe-robert\$.in.	EPO; JPO; DERWENT; IBM_TDB	2003/06/05 13:24